



Data Sheet

Customer:

Part No:

Sample No:

Description:

Item No:

CLS-8013AUG-11

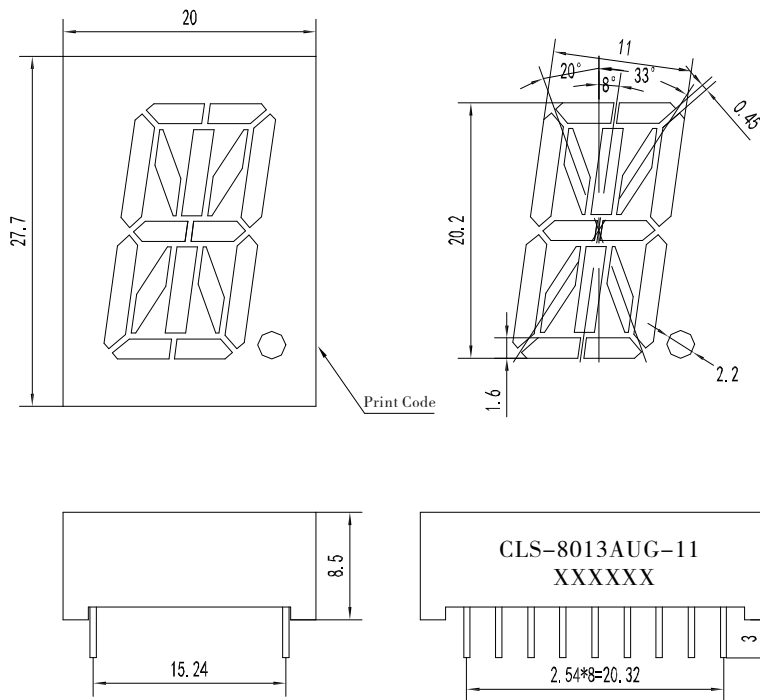
0.8 inch 1 Digit Green Color

Customer			
Check	Inspection	Approval	Date

Descriptions

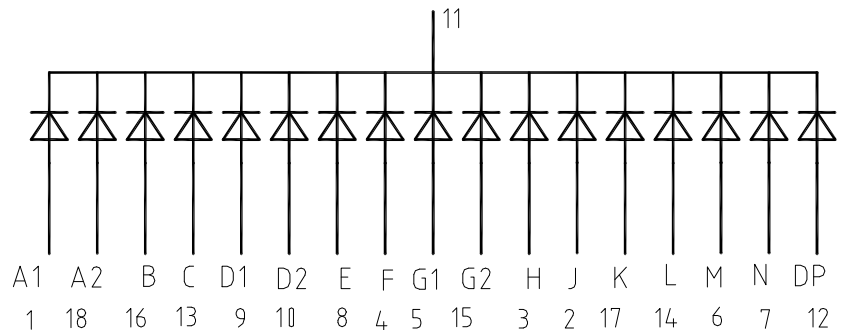
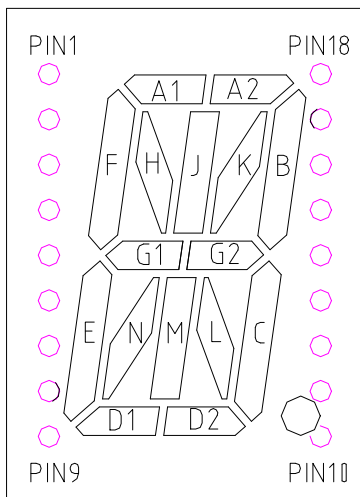
1. Emitting color: Ultra Green
2. Lens color: White Diffused
3. Surface Ink color : Black
4. Dice material: AlGaInP/GaAs

Outline drawing



Tolerance is $\pm 0.25\text{mm}$ unless otherwise noted

Internal Circuit Diagram (C.C.)



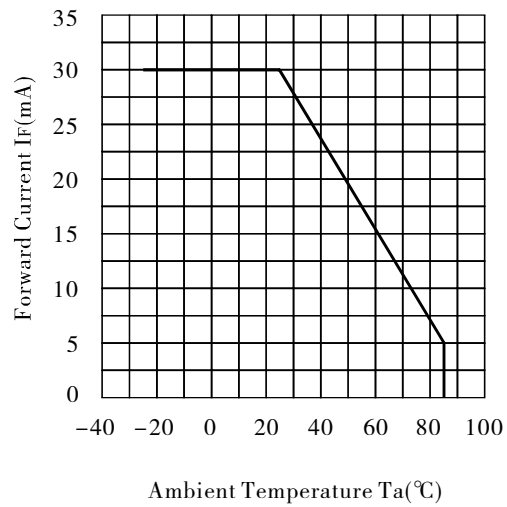
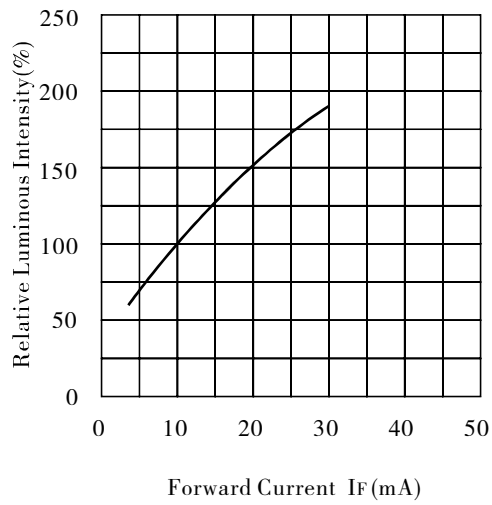
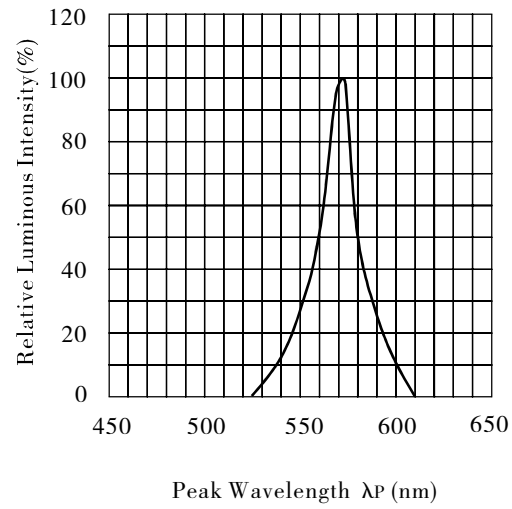
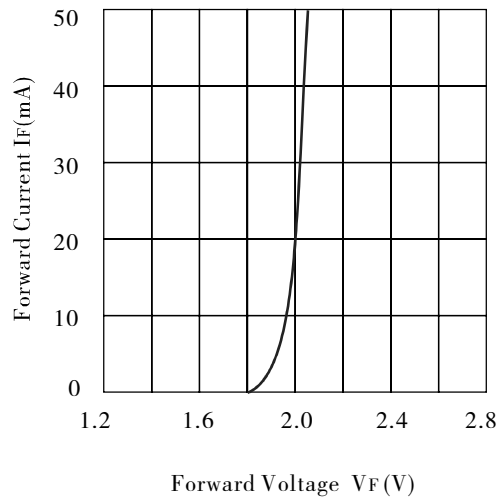
Electrical optical characteristics (Ta=25℃)

Parameter	Symbol	Ultra Green			Unit	Test Condition
		Min	Typ	Max		
Forward Voltage	V_F	---	2.0	2.4	V	IF=20mA
Luminous Intensity	I_v	7.0	13.7	---	mcd	IF=10mA
Peak Wavelength	λ_p	---	572	---	nm	IF=20mA
Dominant Wavelength	λ_d	---	570	---	nm	IF=20mA
Spectral Line half-width	$\Delta\lambda$	---	20	---	nm	IF=20mA
Reverse Leakage Current	I_R	---	---	50	μA	$V_R=5V$

Absolute Maximum Parameters (Ta=25℃)

Parameter	Symbol	Test Condition	Rating	Unit
Power Dissipation	P_D	---	80	mW
Reverse Voltage	V_R	---	5	V
Forward Average Current	I_F	---	30	mA
Temperature Coefficient	I/C	---	0.33	mA/℃
Pulse Current	I_{FP}	Duty=1/10,1kHz	100	mA
Operating Temperature Range	T_{opr}	---	-25 ~ +85	℃
Storage Temperature Range	T_{stg}	---	-30 ~ +100	℃
Soldering Temperature	T_{sd}	---	260℃/5sec	℃

Typical Electro-Optical characteristic curves (Ta=25°C)



Reliability test conditions

Test Item	Test Condition	Result	Judgment criteria
Consecutive operating life test	IF=20mA, T=25℃, t=168h	0/12	Forward Voltage $V_F(V) = \text{Upper Limit} \times 1.2$ Reverse Leakage Current $I_R(\mu A) = \text{Upper Limit} \times 2.0$ Luminous Intensity I_v (mcd)=Lower Limit $\times 0.7$
High temperature storage life test	T=100℃, t=168h	0/12	
Low temperature storage life test	T=-25℃, t=168h	0/12	
high Temperature humidity storage life test	T=85 ± 2℃, RH=85% ± 3, t=168h	0/12	
Temperature cycle test	-25℃~25℃~100℃, 30min 5min 30min 10cycles	0/12	
Thermal shock test	100℃ 0℃ 5min 5min 20 cycles	0/12	
Soldering heat test	T=260 ± 5℃, t=10s ± 1s	0/12	
Solderability test	T=230 ± 5℃, t=5s ± 0.5s	0/12	Steeped Part ≥ 95%
Fall test	h=100cm, Free fall, 3times	0/12	Intact
Terminal strength test	W=9.8N, t=30 ± 5s	0/12	
Lead Bending test	W=4.9N, 2times	0/12	